

Title (en)

METHOD AND APPARATUS FOR ELECTROPLATING A METALLIC DEPOSIT ON INTERCONNECTED METALLIC COMPONENTS AND/OR METALLIZED PRODUCTS

Publication

**EP 0241079 B1 19910911 (EN)**

Application

**EP 87200575 A 19870326**

Priority

NL 8600838 A 19860402

Abstract (en)

[origin: EP0241079A1] Method for electroplating a metallic deposit on interconnected or bandoliered elongate metallic (7') and/or metallized products (7'), whereby providing for non-conductive masking devices between the products (13, 12), of which at least the parts which are in contact with the products (7') consist of resilient material (13) whilst after providing for said masking devices (13) the products (7') are submitted to a contact with an electrolyte.

IPC 1-7

**C25D 5/02; C25D 7/06**

IPC 8 full level

**C25D 5/02** (2006.01); **C25D 7/06** (2006.01)

CPC (source: EP US)

**C25D 5/022** (2013.01 - EP US); **C25D 7/0678** (2013.01 - EP US)

Cited by

EP0328278A1; WO0006806A3

Designated contracting state (EPC)

AT BE CH DE ES FR GB GR IT LI LU NL SE

DOCDB simple family (publication)

**EP 0241079 A1 19871014; EP 0241079 B1 19910911**; AT E67248 T1 19910915; CA 1314519 C 19930316; DE 3772811 D1 19911017; HK 12392 A 19920221; JP H0246677 B2 19901016; JP S6318095 A 19880125; NL 8600838 A 19871102; SG 108591 G 19920214; US 4770754 A 19880913

DOCDB simple family (application)

**EP 87200575 A 19870326**; AT 87200575 T 19870326; CA 533612 A 19870401; DE 3772811 T 19870326; HK 12392 A 19920213; JP 7763287 A 19870401; NL 8600838 A 19860402; SG 108591 A 19911224; US 3257487 A 19870401